Editorial

It is with great pleasure and high hopes that we bring to you the inaugural issue of the new journal christened ***Reviews of Adhesion and Adhesives*** (RAA).

With the explosion of research activity and reports, it is very difficult for busy researchers to stay abreast of the latest developments. So the need for concise and critical reviews of topics of contemporary research interest is quite manifest, and this provides vindication for initiating this journal.

Strictly speaking, adhesion is an interfacial phenomenon; but in a practical sense it is a truly inter-, multi- and transdisciplinary subject. For a holistic approach to adhesion, one has to take due cognizance of interfacial chemistry, rheological behavior of materials and fracture mechanics into consideration. Of course, interfacial chemistry constitutes the marrow of adhesion science but the other two disciplines are of cardinal importance in understanding bond strengths and joint strengths and in devising means to improve adhesion strength in a system of interest. The availability of sophisticated surface analytical techniques has provided a quantum leap in our fundamental understanding of events occurring at a molecular level between mating materials.

This journal is launched with the express intention to provide incisive, illuminating and thought-provoking reviews written by subject matter experts covering all aspects of adhesion science and adhesive technology. The topics to be covered include, but not limited to, fundamental or theoretical aspects of adhesion; modeling of adhesion phenomena; mechanisms of adhesion; surface and interfacial analysis and characterization; unraveling of events at interfaces; characterization of interphases; adhesion of thin films and coatings; adhesion aspects in reinforced composites; formation, characterization, durability and testing of adhesive joints; surface preparation methods; polymer surface modification; biological and dental adhesion; particle adhesion; adhesion of metallized plastics; adhesion of diamond-like films; silanes and other adhesion promoters; contact angle, wettability and adhesion; superhydrophobicity and superhydrophilicity; relevance of adhesion in textiles, printing, coatings, aerospace and a myriad other industries; relevance of adhesion in nanotechnology, e.g., MEMS/NEMS, micro/nanofluidics, nanocomposites and nanotribology; adhesion aspects in microelectronics; novel and high-performance adhesives; green (i.e., biobased) adhesives; medical adhesives; and application of adhesives in a legion of industries.

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Initially the review articles for RAA will be solicited by inviting topflight, world-class researchers to synthesize the information on a particular topic and provide a concise and critical review with his/her personal analysis and perspective. Of course, those who wish to write review articles for RAA are encouraged to submit their articles for consideration for publication in RAA.

The primary responsibility for the success and growth of RAA resides with the editor, but fortunately we have a coterie of luminaries in the broad field of adhesion science and adhesive technology gracing the Editorial Advisory Board (EAB) of RAA, who with their cumulative wisdom will help chart the future of RAA. The EAB of RAA is veritably international in its make-up and its members represent various subspecialties in the broad domain of adhesion science and adhesive technology and they hail from groves of academia and other research organizations.

Initially, the RAA will be published on a quarterly basis with about 4 articles in each issue. This particular inaugural issue contains four critical reviews reflecting very diverse topics, ranging from surface free energy determination to atmospheric plasma surface modification to electrowetting to bioadhesives.

Yours truly and the publisher are very sanguine that RAA will receive a warm welcome from both adhesion veterans as well as budding adhesionists who intend to voyage in the wonderful and fascinating world of adhesion science and adhesive technology.

In closing, I will welcome all comments and suggestions that the readers may have. Please feel free to express your opinions to me regarding any aspects of RAA as this is your journal. Lastly, let me take this opportunity to express my sincere thanks to Martin Scrivener for this steadfast interest and unflinching help in materializing RAA.

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